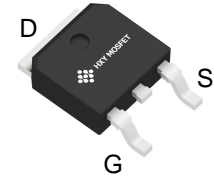




## Description

The SUD35N10-26P uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.



**TO-252-2L  
(TO-252AA)**

## General Features

$V_{DS} = 100V$   $I_D = 50A$

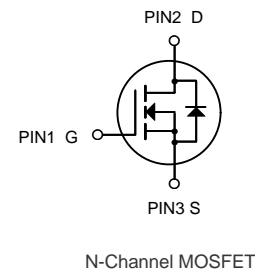
$R_{DS(ON)} < 28m\Omega @ V_{GS}=10V$

## Application

Battery protection

Load switch

Uninterruptible power supply



## Ordering Information

| Product ID   | Pack                | Brand      | Qty(PCS) |
|--------------|---------------------|------------|----------|
| SUD35N10-26P | TO-252-2L(TO-252AA) | HXY MOSFET | 2500     |

## Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$ unless otherwise noted)

| Symbol                        | Parameter  | Rating     | Units              |
|-------------------------------|--|------------|--------------------|
| $V_{DS}$                      | Drain-Source Voltage                             | 100        | V                  |
| $V_{GS}$                      | Gate-Source Voltage                              | $\pm 20$   | V                  |
| $I_D @ T_C=25^\circ\text{C}$  | Continuous Drain Current, $V_{GS} @ 10V^1$       | 50         | A                  |
| $I_D @ T_C=100^\circ\text{C}$ | Continuous Drain Current, $V_{GS} @ 10V^1$       | 30         | A                  |
| $I_{DM}$                      | Pulsed Drain Current <sup>2</sup>                | 150        | A                  |
| EAS                           | Single Pulse Avalanche Energy <sup>3</sup>       | 62.6       | mJ                 |
| $P_D @ T_C=25^\circ\text{C}$  | Total Power Dissipation <sup>4</sup>             | 73         | W                  |
| $T_{STG}$                     | Storage Temperature Range                        | -55 to 150 | $^\circ\text{C}$   |
| $T_J$                         | Operating Junction Temperature Range             | -55 to 150 | $^\circ\text{C}$   |
| $R_{\theta JA}$               | Thermal Resistance Junction-ambient <sup>1</sup> | 62         | $^\circ\text{C/W}$ |
| $R_{\theta JC}$               | Thermal Resistance Junction-Case <sup>1</sup>    | 2.0        | $^\circ\text{C/W}$ |



**Electrical Characteristics** ( $T_J=25^{\circ}\text{C}$  unless otherwise specified)

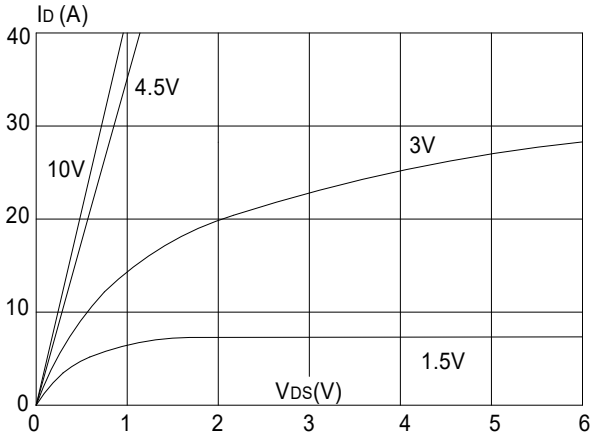
| Symbol        | Parameter   | Test Condition  | Min. | Typ. | Max.      | Units      |
|---------------|---|---|------|------|-----------|------------|
| $V_{(BR)DSS}$ | Drain-Source Breakdown Voltage                            | $V_{GS}=0V, I_D=250\mu A$                             | 100  | -    | -         | V          |
| $I_{DSS}$     | Zero Gate Voltage Drain Current                           | $V_{DS}=100V, V_{GS}=0V,$                             | -    | -    | 1.0       | $\mu A$    |
| $I_{GSS}$     | Gate to Body Leakage Current                              | $V_{DS}=0V, V_{GS}=\pm 20V$                           | -    | -    | $\pm 100$ | nA         |
| $V_{GS(th)}$  | Gate Threshold Voltage                                    | $V_{DS}=V_{GS}, I_D=250\mu A$                         | 2.0  | 2.7  | 4.0       | V          |
| $R_{DS(on)}$  | Static Drain-Source on-Resistance<br><small>note2</small> | $V_{GS}=10V, I_D=20A$                                 | -    | 18   | 28        | m $\Omega$ |
|               |   | $V_{GS}=4.5V, I_D=10A$                                | -    | 22   | 32        | m $\Omega$ |
| $C_{iss}$     | Input Capacitance   | $V_{DS}=25V, V_{GS}=0V,$<br>$f=1.0MHz$                | -    | 3727 | -         | pF         |
| $C_{oss}$     |   |   | -    | 180  | -         | pF         |
| $C_{riss}$    | Reverse Transfer Capacitance                              |   | -    | 148  | -         | pF         |
| $Q_g$         | Total Gate Charge   | $V_{DS}=30V, I_D=15A,$<br>$V_{GS}=10V$                | -    | 40   | -         | nC         |
| $Q_{gs}$      | Gate-Source Charge  |   | -    | 6.2  | -         | nC         |
| $Q_{gd}$      | Gate-Drain("Miller") Charge                               |   | -    | 28   | -         | nC         |
| $t_{d(on)}$   | Turn-on Delay Time  | $V_{DS}=30V, I_D=15A,$<br>$R_G=1.8\Omega, V_{GS}=10V$ | -    | 22   | -         | ns         |
| $t_r$         | Turn-on Rise Time   |   | -    | 182  | -         | ns         |
| $t_{d(off)}$  | Turn-off Delay Time                                       |   | -    | 80   | -         | ns         |
| $t_f$         | Turn-off Fall Time  |   | -    | 142  | -         | ns         |
| $I_S$         | Maximum Continuous Drain to Source Diode Forward Current  |   | -    | -    | 50        | A          |
| $I_{SM}$      | Maximum Pulsed Drain to Source Diode Forward Current      |   | -    | -    | 150       | A          |
| $V_{SD}$      | Drain to Source Diode Forward Voltage                     | $V_{GS}=0V, I_S=30A$                                  | -    | -    | 1.2       | V          |
| $t_{rr}$      | Body Diode Reverse Recovery Time                          | $I_F=30A, di/dt=100A/\mu s$                           | -    | 71   | -         | ns         |
| $Q_{rr}$      | Body Diode Reverse Recovery Charge                        |   | -    | 145  | -         | nC         |

- Notes: 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature  
 2. EAS condition :  $T_J=25^{\circ}\text{C}, V_{DD}=50V, V_G=10V, L=0.5mH, R_g=25\Omega, I_{AS}=14.5A$   
 3. Pulse Test: Pulse Width $\leq 300\mu s$ , Duty Cycle $\leq 0.5\%$

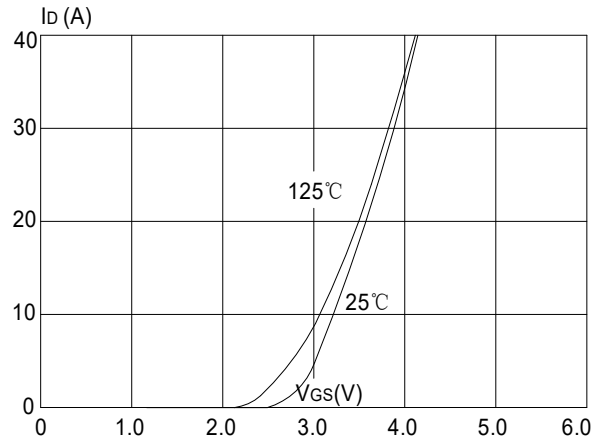


## Typical Performance Characteristics

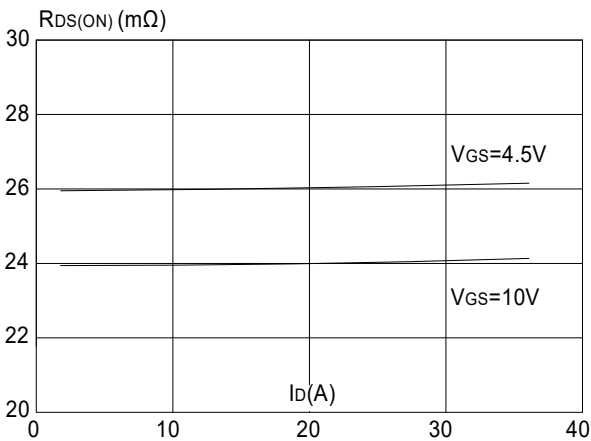
**Figure 1: Output Characteristics**



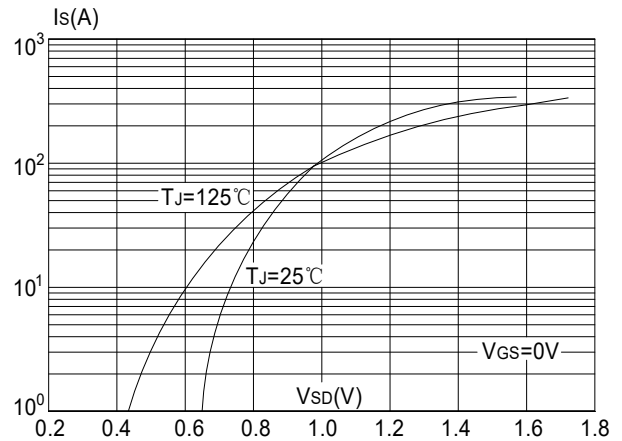
**Figure 2: Typical Transfer Characteristics**



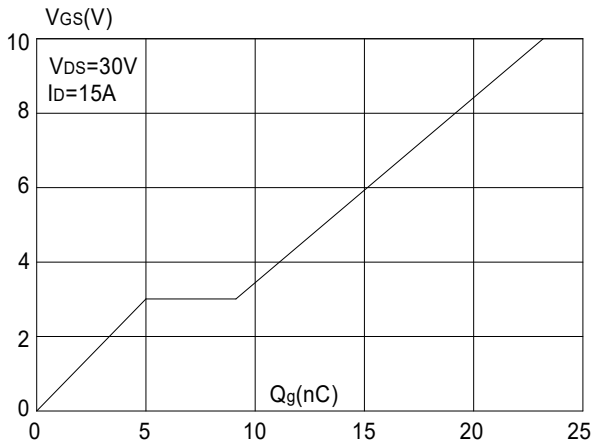
**Figure 3: On-resistance vs. Drain Current**



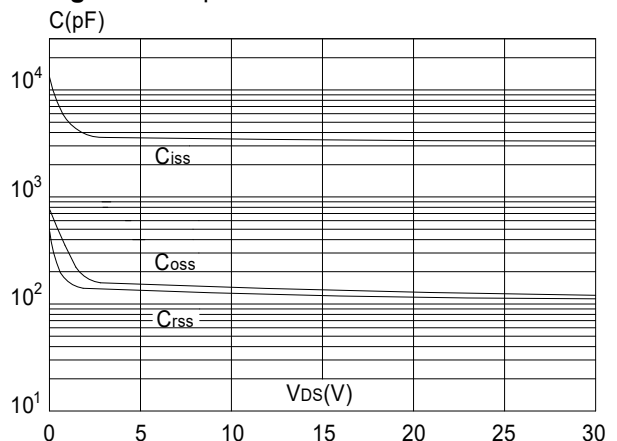
**Figure 4: Body Diode Characteristics**



**Figure 5: Gate Charge Characteristics**

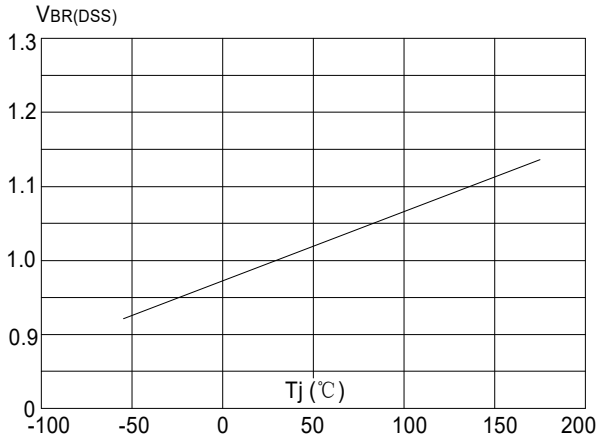


**Figure 6: Capacitance Characteristics**

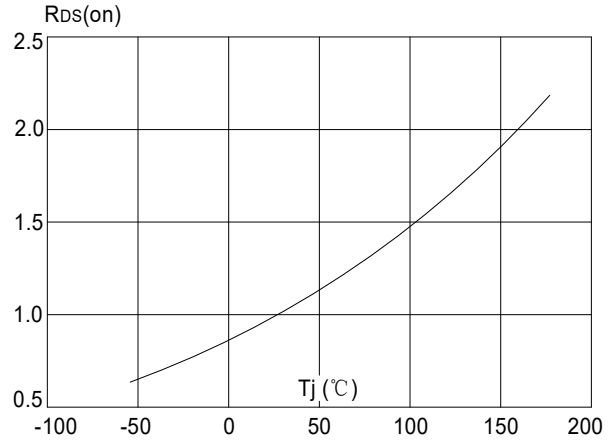




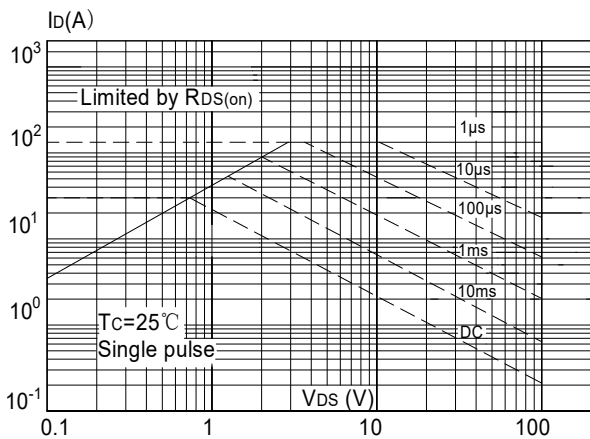
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



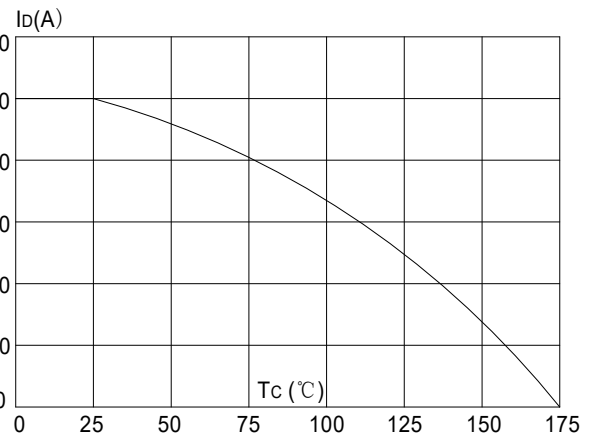
**Figure 8:** Normalized on Resistance vs. Junction Temperature



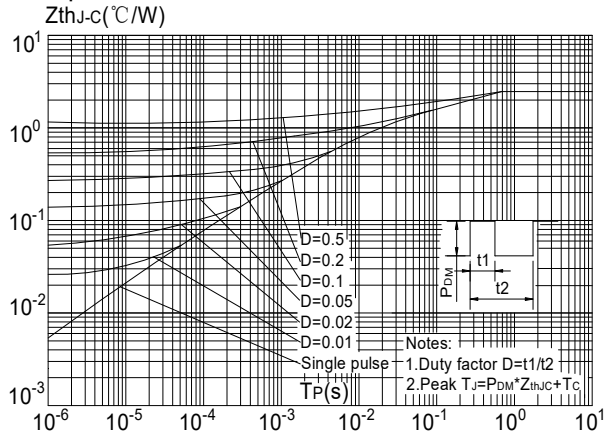
**Figure 9:** Maximum Safe Operating Area



**Figure 10:** Maximum Continuous Drain Current vs. Case Temperature

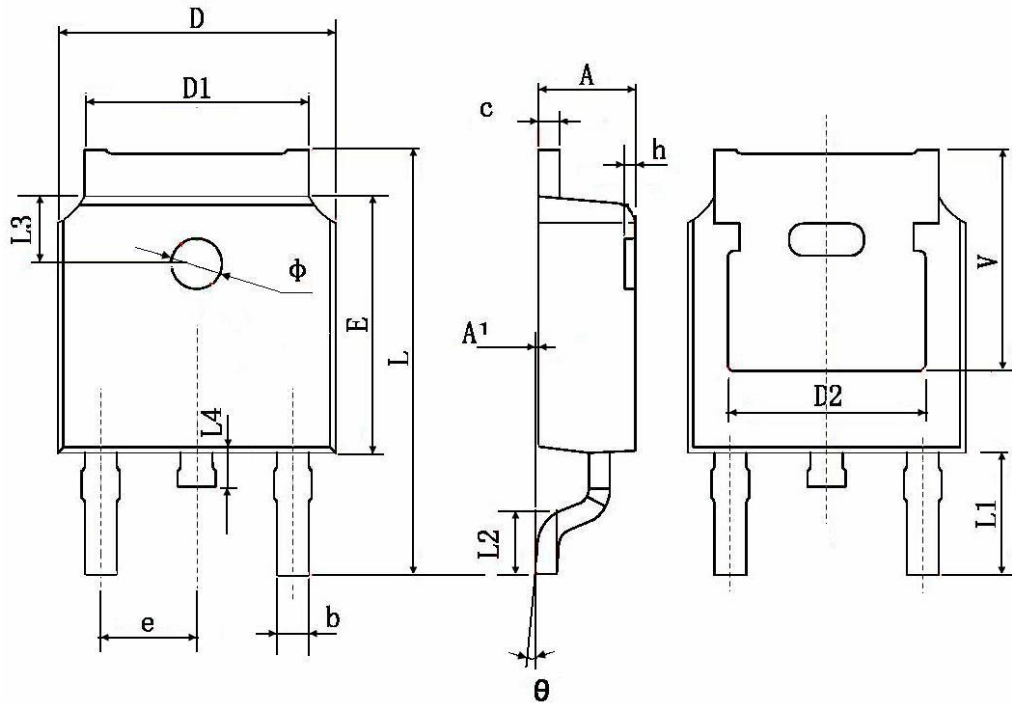


**Figure.11:** Maximum Effective Transient Thermal Impedance, Junction-to-Case





**TO-252-2L(TO-252AA) Package Information**



| Symbol | Dimensions In Millimeters |        | Dimensions In Inches |       |
|--------|---------------------------|--------|----------------------|-------|
|        | Min.                      | Max.   | Min.                 | Max.  |
| A      | 2.200                     | 2.400  | 0.087                | 0.094 |
| A1     | 0.000                     | 0.127  | 0.000                | 0.005 |
| b      | 0.660                     | 0.860  | 0.026                | 0.034 |
| c      | 0.460                     | 0.580  | 0.018                | 0.023 |
| D      | 6.500                     | 6.700  | 0.256                | 0.264 |
| D1     | 5.100                     | 5.460  | 0.201                | 0.215 |
| D2     | 0.483 TYP.                |        | 0.190 TYP.           |       |
| E      | 6.000                     | 6.200  | 0.236                | 0.244 |
| e      | 2.186                     | 2.386  | 0.086                | 0.094 |
| L      | 9.800                     | 10.400 | 0.386                | 0.409 |
| L1     | 2.900 TYP.                |        | 0.114 TYP.           |       |
| L2     | 1.400                     | 1.700  | 0.055                | 0.067 |
| L3     | 1.600 TYP.                |        | 0.063 TYP.           |       |
| L4     | 0.600                     | 1.000  | 0.024                | 0.039 |
| Φ      | 1.100                     | 1.300  | 0.043                | 0.051 |
| θ      | 0°                        | 8°     | 0°                   | 8°    |
| h      | 0.000                     | 0.300  | 0.000                | 0.012 |
| V      | 5.350 TYP.                |        | 0.211 TYP.           |       |



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